

## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	METHOD FOR FABRICATING SEMICONDUCTOR PACKAGES, AND LEADFRAME ASSEMBLIES FOR THE FABRICATION THEREOF	
Application Type:	regular, utility	
Attorney Docket Number:	27-021	
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Customer Number:	22898	*22898*
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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

**Publication Information:**

**Suggested Figure for Publication – FIG. 8**

**Suggested Classification –**

**Suggested Technology Center –**

**Total Number of Drawing Sheets – 5**

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